THE IDEAS COMPANY



Sharp

Since 1912, our company has stood for technological innovation. Even its name comes from an innovation, the "Ever Sharp" automatic pencil. An these innovations are turned into products to meed their users's need.

1915

1987



Ever Sharp Pencil

1960



Colour TVs mass production



Electronic Organizer Big-sreen LCD Projektor

1962



Microwave ovens mass production

1991



8,6" colour LCD TV

1964



Electr. calculator, fully transistorized

1992



16,5" colour TFT-LC-diplay

1969



Gallium-arseniddiode (LED)

1993



ViewCam, Camcorder with LC-display

1973



Pocket calculator with LCD-display

1995



ZR-5000G, mobile communication

Sharp Profile

- Founded in 1912
 - Tokyo, Japan
- **⊃**Business Creed
 - "Sincerity and Creativity"
- DEmployees Worldwide as of April 1, '96
 - 65,100 employees
- **○**No. of Manufacturing Sites **29 in 17 countries**
- ⇒No. of Sales Subsidiaries
 - 21 in 19 countries

- Net Sales in FY'95
 - ¥ 1,281,752 million
- Capital Stock as of Mar.31, '96
 - ¥ 198,325 million
- Capital Investment in FY '95
 - ¥ 138,358 million
- ⇒R & D Investment in FY '95
 - ¥ 115,330 million

Non-consolidated base FY '95: Apr. '95 to Mar. '96

'96 Forecast

Consolidated (Y M, %)

vs. '95

⊃Net Sales : 1,770,000

107.0

Income before

96,000

108.0

Special Items

(5.4)

Net Income

51,000

110.0

(2.9)

'95 Financial Results

Consolidated (YM, %)

	'95	vs.'94	'94
Net Sales	1,650,708	102.0	1,617,620
Operating Income	89,381	111.3	80,311
	(5.4)		(5.0)
Income before	88,499	114.6	77,223
Special Items	(5.4)		(4.8)
Net Income	46,319	104.1	44,508
	(2.8)		(2.8)

^{():} Proportion to net sales

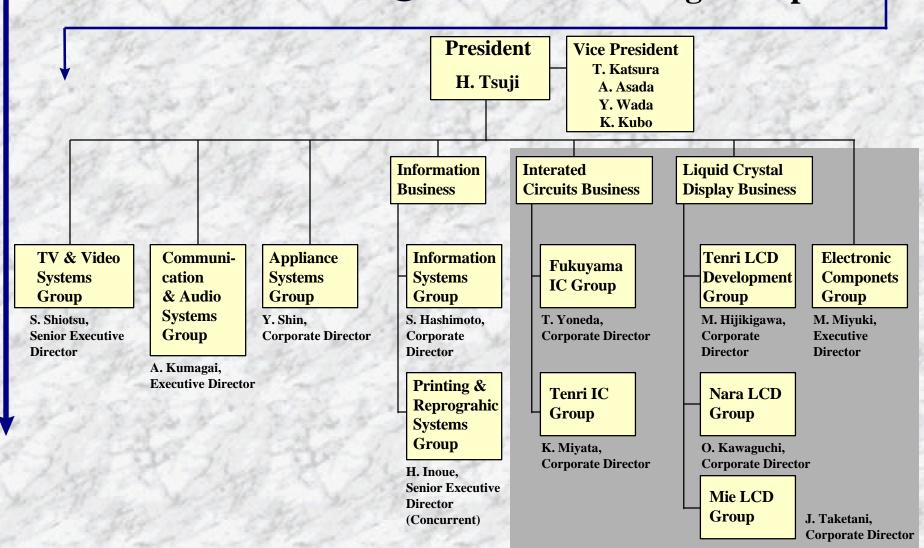
'95 Financial Results

Non-consolidated (Y M, %)

	'95	vs.'94	'94
Net Sales	1,281,752	101.6	1,261,562
Operating Income	57,919	103.3	56,062
_	(4.5)		(4.4)
Income before	70,530	105.2	67,073
Special Items	(5.5)		(5.3)
Net Income	39,372	113.7	34,631
	(3.1)		(2.7)

^{():} Proportion to net sales

11 Manufacturing Groups





International Sales & Marketing Group - IC/Electronic Components

H. Tsuji

President

T. Katsura

Senior Executive Vice President

T. Ishino

Executive Director & Group General Manager

T. Inoue

Corporate Director & Gr. Deputy General Manager Responsible for Sales Group

Marketing/ Administration

O. Uchida

Dept. General Manager Marketing Dept.

Y. Kimura

Dept. General Manager Sales Administartion Dept. (Concurrent)

T. Ishino
General Manager
Device Sales

Electronic Components IC

T. Hamanaka

Dept. General Manager ElectronicComponents Sales Dept.

H. Nakamura

Dept. General Manager IC Sales Dept. I (Tenri)

Y. Kitayama

Dept. General Manager IC Sales Dept. II (Tenri)

(Concurrent)

T. Inoue

General Manager LCD Sales

N. Yamazawa

Dept. General Manager LCD Sales Dept-American & European Operations

T. Tanimoto

Dept. General Manager LCD Sales Dept - Asian Operations H. Iida

General Manager Special Outlets Sales Special Outlets

K. Shimizu

Dept. General Manager 1st Sales Dept.

A. Kurihara

Dept. General Manager 2nd Sales Dept. (Tokyo)

SHARP **Sharp Worldwide -Electronic Componets** Camas Hamburg SEC London SEEG **▲** SMT ▲ SLA Chicago Scotland □ SFDM Seoul SEEG Detroit San Jose Dallas Nuremberg Dublin Wuxi Boston Stuttgart **□** WSEC **♦**Osaka Milano **Head Office** New Jersey Oxford Hong Komg **SEC Head Office ▲** SLE Taipei SRH SECT Irvine Raleigh **▲ STT** Singapore Houston Austin SESL Kaohsiung □ SET Indonesia □ SLE Sharp Head Office Sales Organizations: 6 City **Branch Offices: 17** R&D Sites: 4 Manufacturing Sites: 4



	Modu	les	
	Flat Panel Display	4-bit, 8-bit Sing	
Optoelectronic Devices IR LEDs OPICs Visible LEDs Photocouplers	sive Dot Matrix LCD	Microcomputer Single Chip Systems (32-bit CPU Core)	EDDOM
Full Color LED Units Photo Interruptors Photodiodes	EL Display LCDs with build-in Digitizer	IC Memory Card (JEDEC, PCMC)	DRAMS
Laser Diodes Photodiodes Phototrans Hologram Laser High Power Laser Diodes	SHARP	Flash Memories Pseud FIFOs SRAM	
LCD Back Light Inverters Primary Regulators Chopper Regulators SSRs	LNBs DBS Tuners	HALL ICS HEMT CCDs MMICs LCD D	T Bipolar ICs rivers VLSIs Other LSIs, IC
Low Power-Loss Voltage Regulators CCD Mod Power Devices Hall Devices CD Pick-up Units/Mechan	lules Electronic Tun Wireless LAN	ers Cell-b	ased ASICs
Magneto Otical Disks MD Pick-up Units/Mechanism Magneto Ontical Disk Drives	RF Modulators Cellular RF Units	Space Use Terrestrial Use	Gate Arrays with Built-in Core CPU
on ()there	Fast IR F Components / mmunication Units	Consumer Use Solar Cells / Modu	ASIC

Sharp Europe

- **Subsidiaries in**
- **⊃**Germany
- Sweden
- **⊃**United Kingdom
- **⊃**Belgium
- **⊃**Austria
- **Switzerland**
- **Prance**
- **Italy**
- **Spain**
- **⊃**Netherlands
- **⊃**Denmark

Distributors in Greece
Portugal, Finland, Norway,
Iceland, Russia, Bulgaria,
Romania, Ukraine, Slovenia,
Belarus, Estonia, Lithuania,
Rep. of Kazakhstan, Rep. of
Georgia, Czech Republic,
Slovak Republic, Hungary,
Latvia, Poland, Israel,
Turkey, Malta

Manufacturing in Europe

- **⊃**UK: Copier systems, electronic typewriters, video recorders, microwave ovens.
- France: Telefax systems and copier systems
- Spain: Colour TVs and telefax systems



Development in Europe Sharp Laboratories of Europe Ltd.

- **O**ptoelectronic
- **⊃**Imaging technology
- **⊃**Information technology
- ⇒Liquid crystal
- Strategy & planning
- **Administration**



SEEG

Sharp Electronic (Europe) GmbH Sales in Europe



CED

Consumer Electronics Division

- **⊃**ViewCam
- **O**video printers
- **Occiour TVs**
- **D**video recorders
- **⊃**LCD-projetors
- **Ocordless** telephones
- **Omicrowave ovens**

- **P**air conditioners
- **D**audio systems
- Stereo radio-recorders
- **→** MiniDisc recorders
- **O**cassette-players



ISD

Information Systems Division

- **Ocopier** systems
- **S**scanners
- ⊃laser printers
- **O**telefax systems
- **Inotebooks**
- Delectronic organizers

- **O**calculators
- Delectronic typewriters
- **Ocash registers**



VPE

Visual Presentation Equipment

- ⇒LCD projectors for professional usage with data displays, video displays and multimedia applications
- **⊃**LCD-monitors
- **Ocomputer projection panels**



GSM

- ⇒GSM TQ-G400 Handy Telephone
- **⊃**GSM accessories
- ⇒complete "Mobil Office" incl. Handy, ZR-5000 G and PCMCIA GSM Fax/Datacard

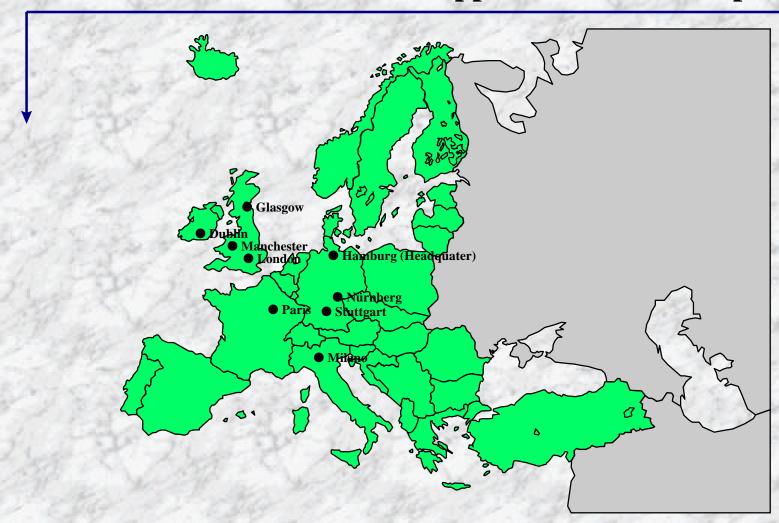


MED

Microelectronics Division

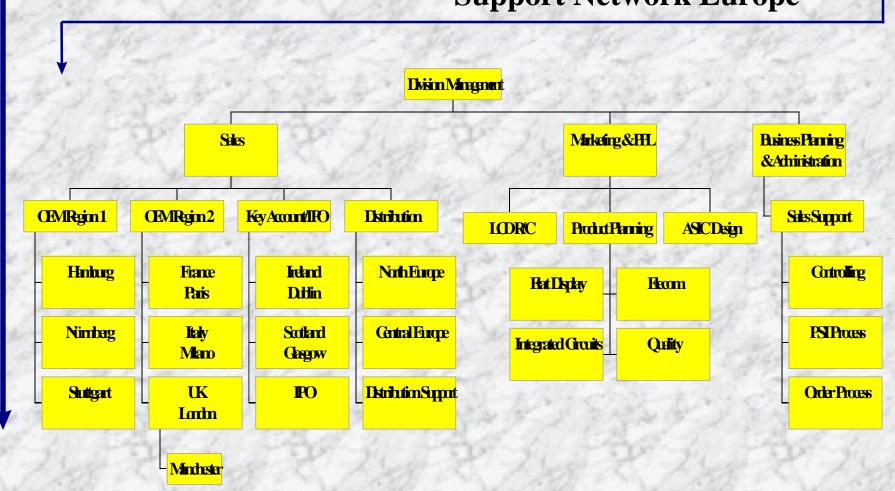
- **⊃**LC-Displays
- Opto-electronic device
- **D**integrated circuits
- **⊃**RF components
- **⇒**Solar cells
- **⊃**CCD`s

SHARP Microelectronics Support Network Europe





SHARP Microelectronics Support Network Europe

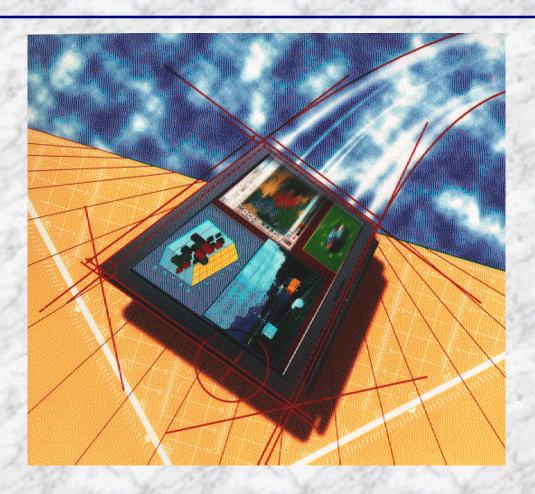




Key Components for Powerful Systems

- >Flat Panel Displays
- Optoelectronic Devices
- **⊃**Power Devices
- **⊃**LED/Laser Components
- **⊃**RF Components
- **⊃**Integrated Circuits
- Mechanical Devices and others
- **⇒**Solar Cells/Modules

• Flat Panel Displays



Accelerating a Multimedia Future

Flat Panel Displays

- **⊃**Colour TFT-LCD Modules
- **○**Colour STN-LCD Modules
- Passive Dot Matrix LCD Modules
- ⇒Electroluminescent Display Modules



Colour TFT-LCD Modules

□TFT for Monitor/FA/OA

- -size: 6.4", 8.4", 10.4", 11.3", 12.1", 13.8", 15", 17.x"
- -Resolution: VGA, SVGA, XGA, SXGA
- -S2-technology for high aperture ratio
- -Wide viewing Angle
- -High brightness, high transmissivity
- -Long life CCFT 25Khrs (typ.)
- -CPP types available
- -High light and het durability



Colour TFT-LCD Modules

TFT for Automotive / AV

- -Size: 3", 4", 5", 5.5", 5.7", 6.4", 7.2", 8.6"
- -Interface: RGB-analog, PAL-composite, NTSC-composite
- -Extended Temp. range (-30°C to +85°C) with integrated backlight
- -Wide Viewing angle (120°)
- -Display rotation function
- -16:9 Aspect ratio



Colour STN-LCD Modules

- Size: 5.5", 8.0", 8.4", 9.4", 10.4", 11.3", 12.1", 13.8", 15", 17.7"
- Resolution: QVGA, VGA, SVGA, XGA
- ⇒High brightness types > 150 cd/m²
- **⊃**Long life CCFT 25 Khrs (typ.)
- **⊃**Mech. compatible to TFT
- Sharp Addressing for improved picture quality



Passive Dot Matrix LCD Modules

- **Resolution:** 16x1, 16x2, 20x2, 40x2, QVGA
- TN, STN with LED backlight
- Standard Interface



Electroluminescent Display Modules

- **⇒**320x240 to 1024x768
- Thigh brightness (200cd/m2)
- **D**upto 16 greyscale
- **⊃**LCD interface
- Thigh contrast moduls (require to circular polarizer)



Optoelectronic Components



Advanced Optoelectronics Technology to Meet Tomorrows's Needs Today



Optoelectronic Components

⊃OPIC*

- *OPIC (Optical IC) is trademark of the SHARP Corporation
- ○Infrared Ermitting Diodes and Photodiodes
- **Photocouplers**
- **Photointerrupters**
- ⇒IR detecting units for remote control
- **⊃**Fiber Optics
- Optical System Device



Main Features of Optoelectronic Components

○Infrared Ermitting Diodes and Photodiodes

- -Models with beam angle for combination with various Photodetectors
- -Double-end models for surface mounting
- -Can-packaged models that provide high-reliability
- -Models with SHARP's OPIC technology to improve function of Photodetector
- -Blue Sensitive Photodiodes
- -Position Sensitive Detectors

Main Features of Optoelectronic Components

Photocouplers

- -High isolation models made using double transfer mold technology <Viso-5.000V>
- -Compact SMD type for automatic molding
- -Half pitch type
- -Wide product line-up approved safety standard UL,TÜV,VDE etc
- -Models with variety of outputs which meet the needs of various applications
 - >> OPIC output for high speed/high functional equipment
 - >> Phototriac/thyristor output for triggering of triac/thyristor for power supplies

Main Features of Optoelectronic Components

Photointerrupters

- -Reflective and transmissive types
- -Models with a variety of shapes and outputs
- -Ultra-compact models made using a two-layer resin
- -High functional models which use our OPIC technology
- -Ultra-compact models with leadless chips for high-density mounting by using MID technology
- -High-resolution models for high-precision detection
- -Suitable for detecting high-speed rotation

Main Features of Optoelectronic Components

⇒IR Detecting Units for Remote Control

- -Compact, thin and ultra compact SMD models with our OPIC technology
- -IR Units with mesh for improved EMI resitance
- -Compatible with various "BPF frequencies"

Main Features of Optoelectronic Components

⇒Fiber Optic

- -High-speed signal transmission (25MB/s for OA equipment, 8MB/s for AV equipment
- -Models with optical mini-jack (for AV equipment) to accommodate optical/analogue/digital signals

Optical Systems Devices

- -High performance due to Position Sensitive Device
- -Distance Measuring Sensors
- -Optical Pointing Device

Power Devices

- **DLCD** Backlight Inverters
- **⊃**Low-Power-Loss Voltage Regulators
- **Chopper Regulators**
- **Primary Regulators**
- Solid State Relais
- **⊃**Phototriac/Photothyristor



Main Features of Power Devices

⊃Low-Power-Loss Voltage Regulator

- -Low power loss that makes it easier to design smaller, lighter, energy-saving equipment. Voltage diffrence between input and output: 0.5 V MAX
- -Multi functional models. (ON/OFF control function, minute adjustable output, variable output, low dissipation current at OFF-state, reset signal generation function etc.)
- -Various build-in protection circuits (Overcurrent, overheat, reverse voltage etc.)
- -4-pin compact, full mold package models (TO-220) Surface mount package models (SC-63)



Main Features of Power Devices

Chopper Regulators

- -Only a few externally attached components required.
- -Various build-in functions (ON/OFF control; overheat; overcurrent protection)
- -Compact surface-mount package

Primary Regulator

- -Build-in power MOS-FET control IC
- -Low-Power-loss due to build in overcurrent protecion circuit



Main Features of Power Devices

Solid State Relais

- -Models with a zero-cross circuit to minimize the generation of noise
- -Models with snubber circuit to control surge current
- -A variety of package styles (SIP,DIP)

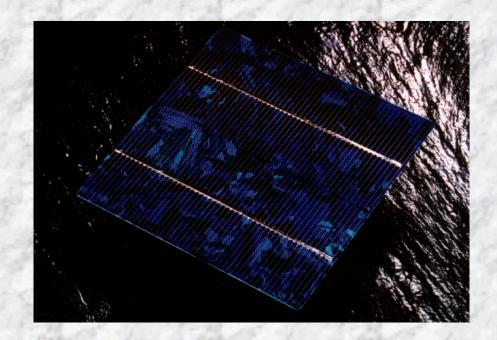
○Phototriac/Photothyristor

- -Various Packages available
- -Output Voltages up to 800 V



Solar Cell/Modules-

- Space Use
- **⊃**Terrestrial Use
- **Consumer Use**





LED/Laser Components

- Through hole LEDs
- SMD LEDs
- **□**LED for Bar Graphic Displays
- **DLED Units**
- **⊃**Laser Diodes



Main Features of Optoelectronic Components

⊃Through hole LEDs

- -Wide variety of packages
- -High brightness materials (AIGaInp, TS AIGaAS)
- -Dichromatic LEDs

SMD LEDs

- -Chipled types
- -MID types (molded interconnected device)
- -Dichromatic and RGB SMD LEDs

LED for bar graph displays

- -seven segment displays
- -Backlightning modules
- -LED arrays for scanners



Main Features of Optoelectronic Components

DLED Units

- -Outdoor Dot Matrix LED units
- -Indoor Dot Matrix LED units
- -Monochrome and Dichromatic and RGB
- -varies sizes and dot pitches
- -Clusters

DLaserdiodes

- -Hologram Lasers
- -Laserdiodes
- -visible and infrared



RF units

- **⊃**LNB-specified for digital broadcasting
- Front End units for digital DBS broadcasting
- ⇒Front End units for digital CATV broadcasting
- **⊃**Tuner for analog DBS reception
- **⊃**RF modulator
- ⇒RF transend units for cordless phones, DECT, CT1, CT1+

Integrated Circuits

- **⊃**Micro Processors
- **→**Memories
- **⇒**ASCICs
- **○**Other ICs



Microcomputers

- **⊃**4-bit, 8-bit Single Chip Microcomputers
- Single Chip Systems (32-bit CPU CORE)



Memories

- **⊃**DRAM's
- ⇒SRAM's
- Pseudo SRAM's
- **⊃**Mask ROM's
- **⊃**Flash Memories
- **⊃**EPROM

- **PFIFO's**
- **⊃**IC Memory Cards JEDEC
 - **PCMCIA**

ASIC's

- **⊃**CPU Core ASSP's
- **⊃**Cell-based ASIC's
- Gate Arrays with Built-in Core CPU
- **□**ARM based ASSP's

Ohter LSI's, IC's

- **⇒**CCD Sensor Chips
- ⇒Hall IC's
- **PHEMT**
- **⊅**MMIC's
- **DLCD** Drivers
- ⇒Bipolar IC's



Mechanical Devices and Others

- **⊃**CCD Modules/Units
- **○**Hall Devices
- **⊃**CD Pick-up Units/Mechanism
- Magneto-Optical Disks
- **⊃**MD Pick-up Units/Mechanism
- **⊃**Magneto-optical Disk Drivers
- **⊃**PCBs